

IN THE CLAIMS

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1. (Presently amended) An assembly for providing solderless electrical connection between of first and second substrates aligned in a stacked configuration, said assembly comprising:

a conductor assembly having at least one elongate conductor adapted to engage a first electrical contact on said first substrate on one end and a second electrical contact on said second substrate on a second end thereof, said conductor having a three-bend hook shape at each end thereof to provide a spring force on each end thereof and

means for retaining said conductor in abutting contact with [at least one of] said first or second contacts and thereby effect an electrical connection between said first contact on said first substrate and said second contact on said second substrate.

2. Canceled

3. Canceled

4. (Previously amended) The invention of Claim 1 wherein said conductor is constrained by a dielectric between the ends thereof.

5. (Original) The invention of Claim 4 wherein said conductor assembly includes a plurality of conductors.

6. (Original) The invention of Claim 5 wherein said conductor assembly is retained within an elongate housing.

7. (Original) The invention of Claim 6 wherein said housing is retained within a frame.

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8. (Original) The invention of Claim 7 wherein said housing is retained within said frame by at least one pin at each end thereof.

9. (Original) The invention of Claim 8 wherein said pin is retained by said frame.

10. (Presently amended) A high density electrical assembly adapted [for use with] to make solderless electrical contacts between plural circuit boards aligned in a stacked configuration, said assembly comprising:

a conductor assembly having plural elongate conductors adapted to engage a first electrical contact on a first circuit board on one end and a second electrical contact on a second circuit board on a second end thereof, each conductor having a three-bend hook shape at each end to provide a spring force on each end thereof and constrained by a dielectric between the ends thereof and

means for retaining each conductor in abutting contact with [at least one of] said first or second contacts and thereby effect an electrical connection between said first contact on said first substrate and said second contact on said second substrate.

11. (Presently amended) A method for providing solderless electrical connection between first and second substrates aligned in a stacked configuration, said method including the steps of:

providing a conductor assembly having at least one elongate conductor adapted to engage a first electrical contact on said first substrate on one end and a second electrical contact on said second substrate on a second end thereof, said conductor being adapted to provide a spring force, and

retaining said conductor in abutting contact with at least one of said first or second contacts and thereby effect an electrical connection between said first contact on said first substrate and said second contact on said second substrate.

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